

#21 P
10/4/99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Lin et al

Serial No. To be assigned

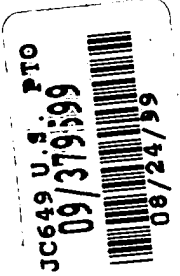
Art Unit: To be assigned

Filed: Concurrently herewith

Examiner: To be assigned

For: Integrated Circuit Package with
Multiple Heat Dissipation Paths

Atty Docket: 0694/00063



**SUBMISSION OF CERTIFIED PRIORITY DOCUMENT(S) and
CLAIM TO PRIORITY UNDER 35 U.S.C. § 119**

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Priority under 35 U.S.C. § 119 is hereby claimed to the following priority document(s),
certified copies of which are enclosed.

<u>Country</u>	<u>Document No.</u>	<u>Filing Date</u>
Taiwan, R.O.C.	88209607	June 11, 1999

Acknowledgement of this claim and submission in the next official communication is
respectfully requested.

Respectfully submitted,

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